



THE LEADER IN HI-TECH TRAINING

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ABOUT THE PRESENTER Leo Lambert Vice President, Technical Director

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### Welcome to the EPTAC Webinar Series: Delamination, Causes and Cures?

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## **Delamination, Causes** and Cures

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## **Delamination**



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What is it? 

- Why is measles not delamination?
- Why is Haloing not delamination?
- Is Crazing a form of delamination?



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## What is it?



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- It is a separation of either the fiberglass from the resin or
- The resin from the laminate or foil, like the prepreg or B stage.



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## **What Causes Delamination**

- Thermal shock
  - Wave solder process
  - Manual soldering
  - Rework and Repair process
- Moisture in the board
- Poor lamination process
- Wrong Tg for FR-4 material



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## What Can Help Prevent Delamination

- Oxide layer on inner layers
- Baking of board prior to thermal processing
- Keeping them dry in storage
- Qualification of supplier to provide boards that are acceptable to the process





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### **Some Typical Stress Testing Parameters**

- Solder Float test 6X @ 288°C
  - Interconnect Stress Test 6X @ 230°C
- n passes in reflow simulation at 260°C
- Time at 260°C must be greater than 10 minutes.



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### **Types of Tests to Measure Delamination**

- Time to delamination is a common measurement used to assess base material performance.
- The time to delamination is a measure of the time it takes for the resin and copper, or resin and reinforcement, to separate or delaminate.
- This test utilizes TMA equipment to bring a sample to a specified temperature and then measures the time it takes for failure to occur.

An Assessment of the Impact of Lead-Free Assembly Processes on Base Material and PCB Reliability Edward Kelley Cookson Electronics, Polyclad Laminates Londonderry, NH





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### **Types of Tests to Measure Delamination**

- Temperatures of 260°C (T260) and 288°C (T288) are commonly used for this testing.
- Many high-Tg FR-4 materials will exhibit *lower* times to delamination than low-Tg FR-4 materials.
- With Pb-free assembly temperatures reaching 260°C, the T260 test has become a much more relevant measure of performance.

An Assessment of the Impact of Lead-Free Assembly Processes on Base Material and PCB Reliability Edward Kelley Cookson Electronics, Polyclad Laminates Londonderry, NH



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## **Delamination Illustration**

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Adapted from IPC-A-600





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### Microsection Delamination Example



 Microsection of laminate separation from the internal foil.

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 This happened after the wave soldering process.

Provided by Assurance Technology Corporation



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## **Microsection example**



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 This manufacturer switched to a 175°C T<sub>g</sub> FR-4 to "avoid problems" with Pb-free assembly.





Adapted from "Final Finishes and Laminate Lead Free Overview" by Joe Renda Enthone OEM Manager



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Figure 5. Times to delamination for FR-4 resins with different glass transition and decomposition temperatures. Source: Cookson Electronics, USA.

### Adapted from Werner Engelmaier PRINTED CIRCUIT BOARD RELIABILITY: NEEDED PCB DESIGN CHANGES FOR LEAD-FREE SOLDERING 15





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## **Measles: Definition and Causes**

### Are a form of separation

- They occurs at the knuckles of the fiber bundles and look like a cross when viewed externally
- Causes can be many, but basically poor preparation of the fiber, lack of wetting of the epoxy and excessive pressure applied during soldering
- Measles will not propagate with exposure to thermal cycle





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## **Example of Measles**



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## **Crazing: Definition and Cause**

- It is a separation along the fiber bundles
- Most times it is caused by mechanical means, such as bending the boards.



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- Crazing is much less controlled separation in the base material forming "interconnections" between measles and possibly adjacent conductive patterns;
- Therefore, the acceptance requirements for crazing were set the same as the similar conditions of delamination and blistering.

Crazing





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## **Crazing Pictures**



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## **Haloing: Definition and Causes**

Is a separation of the epoxy from the glass,

- It occurs either along the edges of the board or around the circumference of a drilled hole. Therefore there is a special criteria for its acceptance and nonconformance
- Board separation process and bad drilling process



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### **On Edges**

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On internal holes



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## **Further Information**

For questions regarding this webinar, please contact Leo Lambert at <u>leo@eptac.com</u>

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